LNJ022X4ARA1

Hight Bright Surface Mounting Chip LED

2214 Type

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	80	mW	
Forward current	I_{F}	20	mA	
Pulse forward current *	I_{FP}	70	mA	
Reverse voltage	V _R	5	V	
Operating ambient temperature	T _{opr}	-40 to +100	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

■ Lighting Color

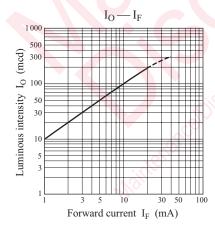
• White

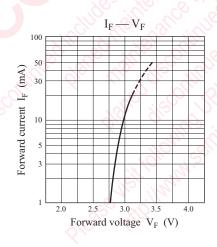
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

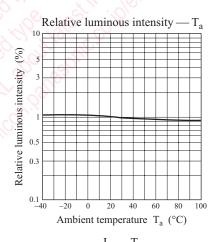
■ Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

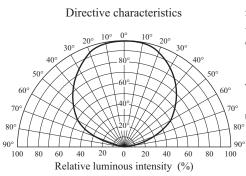
Parameter	Symbol	Co	nditions	Min	Тур	Max	Unit
Luminous intensity *	I_{O}	$I_F = 10 \text{ mA}$	7,000	75	100	165	mcd
Reverse current	I_R	$V_R = 5 V$				100	μΑ
Forward voltage	V _F	$I_F = 10 \text{ mA}$	40		3.00	3.80	V
Characterists and instru	X	$I_F = 10 \text{ mA}$	Miles 148		0.300	ilOI)	_
Chromaticity coordinates	у	$I_F = 10 \text{ mA}$	10 10 10 1	60	0.300	V.o.	_

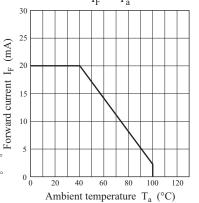
Note) *: Measurement tolerance: ±20%







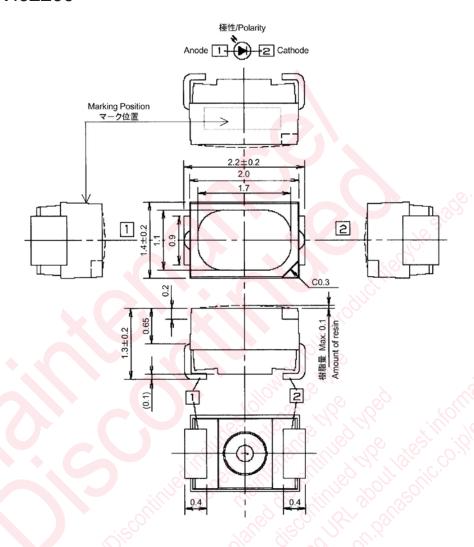




LNJ022X4ARA1 Panasonic

■ Package (Unit: mm)

LLDFTR4J2200



- Pin name
 - 1: Anode
 - 2: Cathode

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